CLAIMS

1. A process of fabricating a printed circuit board, the process comprising:

providing a first sheet of dielectric material including a first top surface having at least one first conductive trace and a second sheet of dielectric material including a second top surface having at least one second conductive trace;

depositing a first solder bump on the at least one first conductive trace;

applying the second sheet of dielectric material to the first sheet of dielectric material with bonding film sandwiched in between;

bonding the first and second sheets of dielectric material to one another;

providing a conductive material to connect the first solder bump on the at least one first conductive trace to the at least one second conductive trace;

depositing a second solder bump on the at least one second conductive trace; and

removing a portion of the second sheet of dielectric material between the first solder bump and the second solder bump to create a ramp between the first solder bump and the second solder bump,

wherein the ramp is formed by milling along a continuous path through the first solder bump, the second sheet of dielectric material, the at least one second conductive trace, and the second solder bump,

wherein the process of providing a conductive material is by depositing the conductive material over the ramp between the first solder bump and the second solder bump.

2. The process of claim 1, wherein the process of milling is to provide a clean surface for soldering.

3. The process of claim 1, wherein the conductive interconnection is performed by an aerosol jet process configured to use aerodynamic focusing to precisely and accurately deposit electronic inks between the first solder bump and the second solder bump.

4. The process of claim 1, wherein the first solder bump is located between the first sheet of the dielectric material and the second sheet of dielectric material.

5. The process of claim 4, wherein the second conductive trace includes a ground plane.

6. The process of claim 1, wherein the first solder bump includes lead-based or lead-free solder.

7. The process of claim 1, wherein bonding the first and second sheets of dielectric material to one another includes curing the sheets under pressure and temperature to form an integral final product.